

	Type	L #	Hits	Search Text
1	BRS	L1	32266 5	((semiconductor or wafer\$1 or chip\$1 or (integrated adj circuit\$3) or ic\$2) near7 (fab\$8 or manufactur\$3 or processing)).ti,ab.
2	BRS	L2	330	1 and (skip\$ near7 (process\$3 or step\$1 or judgement))
3	BRS	L3	23	1 and (skip\$ near7 (process\$3 or step\$1 or judgement))
4	BRS	L4	307	1 and (skip\$ near7 (process\$3 or step\$1 or judgement))
5	BRS	L5	18	(((semiconductor or wafer\$1 or chip\$1 or (integrated adj circuit\$3) or ic\$2) near7 (fab\$8 or manufactur\$3 or processing)).ti,ab.) and (skip\$ near7 (process\$3 or step\$1) near7 (judg\$5 or determin\$3))
6	BRS	L6	0	(((semiconductor or wafer\$1 or chip\$1 or (integrated adj circuit\$3) or ic\$2) near7 (fab\$8 or manufactur\$3 or processing)).ti,ab.) and (skip\$ near7 (process\$3 or step\$1) near7 (judg\$5 or determin\$3))
7	BRS	L7	32282 8	((semiconductor or wafer\$1 or chip\$1 or (integrated adj circuit\$3) or ic\$2) near7 (fab\$8 or manufactur\$3 or processing)).ti,ab.
8	BRS	L8	18	(((semiconductor or wafer\$1 or chip\$1 or (integrated adj circuit\$3) or ic\$2) near7 (fab\$8 or manufactur\$3 or processing)).ti,ab.) and (skip\$ near7 (process\$3 or step\$1) near7 (judg\$5 or determin\$3))

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	DBs	Time Stamp	C o m m e n t s	E r r o r s
1	USPAT; US-PGPUB ; EPO; JPO; DERWENT	2004/09/08 15:18		0
2	USPAT; US-PGPUB ; EPO; JPO; DERWENT	2004/09/08 15:20		0
3	EPO; JPO; DERWENT	2004/09/08 15:21		0
4	USPAT; US-PGPUB	2004/09/08 15:21		0
5	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:22		0
6	EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:23		0
7	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:24		0
8	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:24		0

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	Type	L #	Hits	Search Text
9	BRS	L9	8	(((semiconductor or wafer\$1 or chip\$1 or (integrated adj circuit\$3) or ic\$2) near7 (fab\$8 or manufactur\$3 or processing)).ti,ab.) and ((bypass\$3 or (by adj pass\$3)) near7 (process\$3 or step\$1) near7 (judg\$5 or determin\$3))
10	BRS	L10	10	(((semiconductor or wafer\$1 or chip\$1 or (integrated adj circuit\$3) or ic\$2) near7 (fab\$8 or manufactur\$3 or processing)).ti,ab.) and ((omit\$5 or omission) near7 (process\$3 or step\$1) near7 (judg\$5 or determin\$3))
11	BRS	L11	47	(((semiconductor or wafer\$1 or chip\$1 or (integrated adj circuit\$3) or ic\$2) near7 (fab\$8 or manufactur\$3 or processing)).ti,ab.) and ((eliminat\$4) near7 (process\$3 or step\$1) near7 (judg\$5 or determin\$3))

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	DBs	Time Stamp	Comments	Errors
9	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:25		0
10	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:26		0
11	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:26		0

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